

**Amendments to the Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently Amended) A method of forming a dielectric filler-containing polyimide coating on a metallic material, comprising forming through an electrodeposition coating ~~method with the use of~~ by using a dielectric filler-containing polyimide electrodeposition solution, said solution being a polyimide electrodeposition solution ~~in which~~ containing a dielectric filler ~~has been contained~~,

wherein ~~the used as a~~ dielectric filler is a globoid dielectric powder having a perovskite structure which has an average particle size, is 0.05 to 1.0  $\mu\text{m}$  in an average particle size  $D_{IA}$ , of 0.05 to 1.0  $\mu\text{m}$ , a weight cumulative particle size, 0.1 to 2.0  $\mu\text{m}$  in a weight cumulative particle size  $D_{50}$ , of 0.1 to 2.0  $\mu\text{m}$  based on a laser diffraction scattering particle size distribution measurements method, and a coagulation degree value,  $D_{50}/D_{IA}$ , of 4.5 or less in a coagulation degree value represented by  $D_{50}/D_{IA}$  where the weight cumulative particle size  $D_{50}$  and the average particle size  $D_{IA}$  are obtained from an image analysis.

2. (Currently Amended) A method of forming a dielectric filler-containing polyimide coating on a metallic material, comprising forming through an electrodeposition coating ~~method with the use of~~ by using a dielectric filler-containing polyimide electrodeposition

solution, said solution being a polyimide electrodeposition solution ~~in which~~ containing a dielectric filler ~~has been contained~~,

wherein the method ~~comprising the steps of~~ comprises:

forming on a surface of a copper material a metallic seed layer of either nickel or cobalt; and

forming on ~~a surface of said copper material~~ a the metallic seed layer an electrodeposition coating comprising a dielectric filler-containing polyimide coating ~~through an electrodeposition coating method with the use of~~ formed from a dielectric filler-containing polyimide electrodeposition solution, said solution containing a dielectric powder as a dielectric filler, said dielectric powder having a perovskite structure which has an average particle size, is 0.05 to 1.0  $\mu\text{m}$  in an average particle size  $D_{IA}$ , of 0.05 to 1.0  $\mu\text{m}$ , a weight cumulative particle size, 0.1 to 2.0  $\mu\text{m}$  in a weight cumulative particle size  $D_{50}$ , of 0.1 to 2.0  $\mu\text{m}$  based on a laser diffraction scattering particle size distribution measurements method, and a coagulation degree value,  $D_{50}/D_{IA}$ , of 4.5 or less in a coagulation degree value represented by  $D_{50}/D_{IA}$  where the weight cumulative particle size  $D_{50}$  and the average particle size  $D_{IA}$  are obtained from an image analysis.

3. (Currently Amended) The A method of forming a dielectric filler-containing polyimide coating on a metallic material according to claim 1, wherein a the content of the dielectric filler in the dielectric filler-containing polyimide electrodeposition solution is 50g/L to 350g/L.

4. (Currently Amended) The A method of ~~forming a dielectric filler containing polyimide coating on a metallic material according to~~ claim 1, wherein the dielectric filler is selected from the group consisting of either calcined barium titanate ~~or~~ and uncalcined barium titanate.

5. (Currently Amended) The A method of ~~forming a dielectric filler containing polyimide coating on a metallic material according to~~ claim 1, wherein the dielectric filler is a barium titanate having a crystal structure selected from the group consisting of either only a cubic crystal structure ~~only or~~ and a crystal structure of a mixed state between a cubic crystal structure and a tetragonal crystal structure.

6. (Currently Amended) A method of manufacturing a copper clad laminate for forming a capacitor layer for use in a printed wiring board, said copper clad laminate having a layered structure consisting of a first copper foil, a dielectric filler-containing polyimide dielectric layer, and a second copper foil, comprising the steps of:  
employing providing a first copper foil having a dielectric filler-containing polyimide coating and a second copper foil having a polyimide thin film ~~being a polyimide thin film~~ formed on one side of said second copper foil, said dielectric filler-containing polyimide coating having a dielectric filler-containing polyimide coating formed on a surface of said first copper foil through an electrodeposition coating ~~method with the use of~~ by using a dielectric filler-containing polyimide electrodeposition solution, said dielectric filler-containing polyimide electrodeposition solution being prepared through mixing a polyimide electrodeposition solution and a dielectric powder, ~~as a~~

~~dielectric filler, wherein the dielectric powder has a having perovskite structure which~~  
~~having an average particle size, is 0.05 to 1.0  $\mu\text{m}$  in an average particle size  $D_{IA}$ , of 0.05~~  
~~to 1.0  $\mu\text{m}$ , a weight cumulative particle size, 0.1 to 2.0  $\mu\text{m}$  in a weight cumulative~~  
~~particle size  $D_{50}$ , of 0.1 to 2.0  $\mu\text{m}$  based on a laser diffraction scattering particle size~~  
~~distribution measurements method, and a coagulation degree value,  $D_{50}/D_{IA}$ , of 4.5 or~~  
~~less in a coagulation degree value represented by  $D_{50}/D_{IA}$  where the weight cumulative~~  
~~particle size  $D_{50}$  and the average particle size  $D_{IA}$  are obtained from an image analysis;~~  
and

laminating a surface of the dielectric filler-containing polyimide coating of said  
first copper foil ~~having a dielectric filler-containing polyimide coating~~ and a surface of the  
polyimide thin film of said second copper foil ~~having a polyimide thin film~~ in a manner that  
both the surfaces come into contact with each other.

7. (Currently Amended) A method of manufacturing a copper clad laminate for  
forming a capacitor layer for use in a printed wiring board, said copper clad laminate  
having a layered structure consisting of a first copper foil, a dielectric filler-containing  
polyimide dielectric layer, and a second copper foil, comprising ~~the steps of:~~

forming a metallic seed layer of either nickel or cobalt on a surface of a first  
copper foil;

~~employing~~ providing a first copper foil having a dielectric filler-containing  
polyimide coating and a second copper foil having a polyimide thin film ~~being a~~  
~~polyimide thin film~~ formed on one side of said second copper foil, said ~~dielectric filler-~~  
~~containing polyimide coating having a~~ dielectric filler-containing polyimide coating

formed on a surface of said metal seed layer ~~through an~~ by electrodepositing a  
~~electrodeposition coating method with the use of~~ from a dielectric filler-containing  
polyimide electrodeposition solution, said dielectric filler-containing polyimide  
electrodeposition solution being prepared ~~through~~ by mixing a polyimide  
electrodeposition solution and a dielectric powder, ~~as a dielectric filler,~~ wherein the  
dielectric powder has a having perovskite structure which with an average particle size,  
is 0.05 to 1.0  $\mu\text{m}$  in an average particle size  $D_{IA}$ , of 0.05 to 1.0  $\mu\text{m}$ , a weight cumulative  
particle size, 0.1 to 2.0  $\mu\text{m}$  in a weight cumulative particle size  $D_{50}$ , of 0.1 to 2.0  $\mu\text{m}$   
based on a laser diffraction scattering particle size distribution measurements method,  
and a coagulation degree value,  $D_{50}/D_{IA}$ , of 4.5 or less in a coagulation degree value  
represented by  $D_{50}/D_{IA}$  where the weight cumulative particle size  $D_{50}$  and the average  
particle size  $D_{IA}$  are obtained from an image analysis; and

laminating a surface of the dielectric filler-containing polyimide coating of said  
first copper foil ~~having a dielectric filler-containing polyimide coating~~ and a surface of the  
polyimide thin film of said second copper foil ~~having a polyimide thin film~~ in a manner that  
both the surfaces come into contact with each other.

8. (Currently Amended) The A method of ~~forming a dielectric filler-containing~~  
~~polyimide coating on a metallic material according to claim 6,~~ wherein a the content of  
the dielectric filler in the dielectric filler-containing polyimide electrodeposition solution is  
50g/L to 350g/L.

9. (Currently Amended) ~~The A method of forming a copper clad laminate for forming a capacitor layer for use in a printed wiring board according to claim 6, wherein the dielectric filler is selected from the group consisting of either calcined barium titanate or and uncalcined barium titanate.~~

10. (Currently Amended) ~~The A method of forming a dielectric filler containing polyimide coating on a metallic material according to claim 6, wherein the dielectric filler is a barium titanate having a crystal structure selected from the group consisting of either only a cubic crystal structure only or and a crystal structure of a mixed state between a cubic crystal structure and a tetragonal crystal structure.~~

11. (Currently Amended) A copper clad laminate for forming a capacitor layer for use in a printed wiring board ~~as obtained through the methods of forming a copper clad laminate for forming a capacitor layer for use in a printed wiring board~~ wherein the laminate is made according to the method of claim 6.

12. (Currently Amended) ~~The A method of forming a dielectric filler containing polyimide coating on a metallic material according to claim 2, wherein a the content of the dielectric filler in the dielectric filler-containing polyimide electrodeposition solution is 50g/L to 350g/L.~~

13. (Currently Amended) ~~The A method of forming a dielectric filler containing polyimide coating on a metallic material according to claim 2, wherein the dielectric filler~~

is selected from the group consisting of either calcined barium titanate or and  
uncalcined barium titanate.

14. (Currently Amended) ~~The A method of forming a dielectric filler containing polyimide coating on a metallic material according to claim 2, wherein the dielectric filler is a barium titanate having a crystal structure selected from the group consisting of either only a cubic crystal structure only or and a crystal structure of a mixed state between a cubic crystal structure and a tetragonal crystal structure.~~

15. (Currently Amended) ~~The A method of forming a dielectric filler containing polyimide coating on a metallic material according to claim 7, wherein a the content of the dielectric filler in the dielectric filler-containing polyimide electrodeposition solution is 50g/L to 350g/L.~~

16. (Currently Amended) ~~The A method of forming a dielectric filler containing polyimide coating on a metallic material according to claim 7, wherein the dielectric filler is selected from the group consisting of either calcined barium titanate or and uncalcined barium titanate.~~

17. (Currently Amended) ~~The A method of forming a dielectric filler containing polyimide coating on a metallic material according to claim 7, wherein the dielectric filler is a barium titanate having a crystal structure selected from the group consisting of~~

~~either~~ only a cubic crystal structure ~~only or~~ and a crystal structure of a mixed state between a cubic crystal structure and a tetragonal crystal structure.

18. (Currently Amended) A copper clad laminate for forming a capacitor layer for use in a printed wiring board ~~as obtained through the methods of forming a copper clad laminate for forming a capacitor layer for use in a printed wiring board~~ wherein the laminate is produced according to the method of claim 7.